


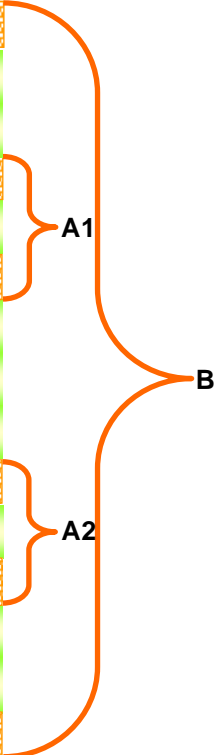









Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 159 FR4 35 L10.35 P18_10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_159_FR4_35_L10.35_p18_10

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		
	180 μ	Prepreg		
Layer-2	180 μ	Prepreg		
	35 μ	Copper		
Layer-3	100 μ	L-FR4		
	35 μ	Copper		
Layer-4	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-5	100 μ	Prepreg		
	35 μ	Copper		
Layer-99	100 μ	L-FR4		
	35 μ	Copper		
Layer-99	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-99	35 μ	Copper		

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